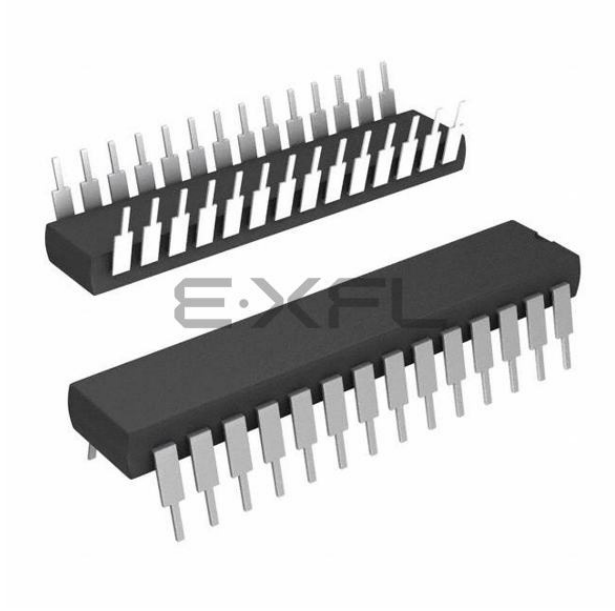

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	32MHz
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, HLVD, POR, PWM, WDT
Number of I/O	23
Program Memory Size	16KB (5.5K x 24)
Program Memory Type	FLASH
EEPROM Size	512 x 8
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5.5V
Data Converters	A/D 13x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	28-DIP (0.300", 7.62mm)
Supplier Device Package	28-SPDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24fv16ka302-i-sp

TABLE 1-3: PIC24FV32KA304 FAMILY PINOUT DESCRIPTIONS (CONTINUED)

Function	F					FV					I/O	Buffer	Description
	Pin Number					Pin Number							
	20-Pin PDIP/ SSOP/ SOIC	28-Pin SPDIP/ SSOP/ SOIC	28-Pin QFN	44-Pin QFN/ TQFP	48-Pin UQFN	20-Pin PDIP/ SSOP/ SOIC	28-Pin SPDIP/ SSOP/ SOIC	28-Pin QFN	44-Pin QFN/ TQFP	48-Pin UQFN			
RC0	—	—	—	25	27	—	—	—	25	27	I/O	ST	PORTC Pins
RC1	—	—	—	26	28	—	—	—	26	28	I/O	ST	
RC2	—	—	—	27	29	—	—	—	27	29	I/O	ST	
RC3	—	—	—	36	39	—	—	—	36	39	I/O	ST	
RC4	—	—	—	37	40	—	—	—	37	40	I/O	ST	
RC5	—	—	—	38	41	—	—	—	38	41	I/O	ST	
RC6	—	—	—	2	2	—	—	—	2	2	I/O	ST	
RC7	—	—	—	3	3	—	—	—	3	3	I/O	ST	
RC8	—	—	—	4	4	—	—	—	4	4	I/O	ST	
RC9	—	—	—	5	5	—	—	—	5	5	I/O	ST	
REFO	18	26	23	15	16	18	26	23	15	16	O	—	Reference Clock Output
RTCC	17	25	22	14	15	17	25	22	14	15	O	—	Real-Time Clock/Calendar Output
SCK1	15	22	19	9	10	15	22	19	9	10	I/O	ST	SPI1 Serial Input/Output Clock
SCK2	2	14	11	38	41	2	14	11	38	41	I/O	ST	SPI2 Serial Input/Output Clock
SCL1	12	17	14	44	48	12	17	14	44	48	I/O	I^2C	I2C1 Clock Input/Output
SCL2	18	7	4	24	26	18	7	4	24	26	I/O	I^2C	I2C2 Clock Input/Output
SCLKI	10	12	9	34	37	10	12	9	34	37	I	ST	Digital Secondary Clock Input
SDA1	13	18	15	1	1	13	18	15	1	1	I/O	I^2C	I2C1 Data Input/Output
SDA2	6	6	3	23	25	6	6	3	23	25	I/O	I^2C	I2C2 Data Input/Output
SDI1	17	21	18	8	9	17	21	18	8	9	I	ST	SPI1 Serial Data Input
SDI2	4	19	16	36	39	4	19	16	36	39	I	ST	SPI2 Serial Data Input
SDO1	16	24	21	11	12	16	24	21	11	12	O	—	SPI1 Serial Data Output
SDO2	3	15	12	37	40	3	15	12	37	40	O	—	SPI2 Serial Data Output
SOSCI	9	11	8	33	36	9	11	8	33	36	I	ANA	Secondary Oscillator Input
SOSCO	10	12	9	34	37	10	12	9	34	37	O	ANA	Secondary Oscillator Output
$\overline{SS1}$	18	26	23	15	16	18	26	23	15	16	O	—	SPI1 Slave Select
$\overline{SS2}$	15	23	20	35	38	15	23	20	35	38	O	—	SPI2 Slave Select

2.2 Power Supply Pins

2.2.1 DECOUPLING CAPACITORS

The use of decoupling capacitors on every pair of power supply pins, such as VDD, VSS, AVDD and AVSS, is required.

Consider the following criteria when using decoupling capacitors:

- **Value and type of capacitor:** A 0.1 μF (100 nF), 10-20V capacitor is recommended. The capacitor should be a low-ESR device, with a resonance frequency in the range of 200 MHz and higher. Ceramic capacitors are recommended.
- **Placement on the printed circuit board:** The decoupling capacitors should be placed as close to the pins as possible. It is recommended to place the capacitors on the same side of the board as the device. If space is constricted, the capacitor can be placed on another layer on the PCB using a via; however, ensure that the trace length from the pin to the capacitor is no greater than 0.25 inch (6 mm).
- **Handling high-frequency noise:** If the board is experiencing high-frequency noise (upward of tens of MHz), add a second ceramic type capacitor in parallel to the above described decoupling capacitor. The value of the second capacitor can be in the range of 0.01 μF to 0.001 μF. Place this second capacitor next to each primary decoupling capacitor. In high-speed circuit designs, consider implementing a decade pair of capacitances as close to the power and ground pins as possible (e.g., 0.1 μF in parallel with 0.001 μF).
- **Maximizing performance:** On the board layout from the power supply circuit, run the power and return traces to the decoupling capacitors first, and then to the device pins. This ensures that the decoupling capacitors are first in the power chain. Equally important is to keep the trace length between the capacitor and the power pins to a minimum, thereby reducing PCB trace inductance.

2.2.2 TANK CAPACITORS

On boards with power traces running longer than six inches in length, it is suggested to use a tank capacitor for integrated circuits, including microcontrollers, to supply a local power source. The value of the tank capacitor should be determined based on the trace resistance that connects the power supply source to the device, and the maximum current drawn by the device in the application. In other words, select the tank capacitor so that it meets the acceptable voltage sag at the device. Typical values range from 4.7 μF to 47 μF.

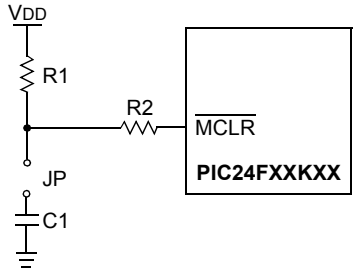
2.3 Master Clear ($\overline{\text{MCLR}}$) Pin

The $\overline{\text{MCLR}}$ pin provides two specific device functions: Device Reset, and Device Programming and Debugging. If programming and debugging are not required in the end application, a direct connection to VDD may be all that is required. The addition of other components, to help increase the application's resistance to spurious Resets from voltage sags, may be beneficial. A typical configuration is shown in Figure 2-1. Other circuit designs may be implemented, depending on the application's requirements.

During programming and debugging, the resistance and capacitance that can be added to the pin must be considered. Device programmers and debuggers drive the $\overline{\text{MCLR}}$ pin. Consequently, specific voltage levels (VIH and VIL) and fast signal transitions must not be adversely affected. Therefore, specific values of R1 and C1 will need to be adjusted based on the application and PCB requirements. For example, it is recommended that the capacitor, C1, be isolated from the $\overline{\text{MCLR}}$ pin during programming and debugging operations by using a jumper (Figure 2-2). The jumper is replaced for normal run-time operations.

Any components associated with the $\overline{\text{MCLR}}$ pin should be placed within 0.25 inch (6 mm) of the pin.

FIGURE 2-2: EXAMPLE OF $\overline{\text{MCLR}}$ PIN CONNECTIONS



Note 1: R1 ≤ 10 kΩ is recommended. A suggested starting value is 10 kΩ. Ensure that the $\overline{\text{MCLR}}$ pin VIH and VIL specifications are met.

2: R2 ≤ 470Ω will limit any current flowing into $\overline{\text{MCLR}}$ from the external capacitor, C, in the event of $\overline{\text{MCLR}}$ pin breakdown due to Electrostatic Discharge (ESD) or Electrical Overstress (EOS). Ensure that the $\overline{\text{MCLR}}$ pin VIH and VIL specifications are met.

4.2 Data Address Space

The PIC24F core has a separate, 16-bit wide data memory space, addressable as a single linear range. The data space is accessed using two Address Generation Units (AGUs), one each for read and write operations. The data space memory map is shown in Figure 4-3.

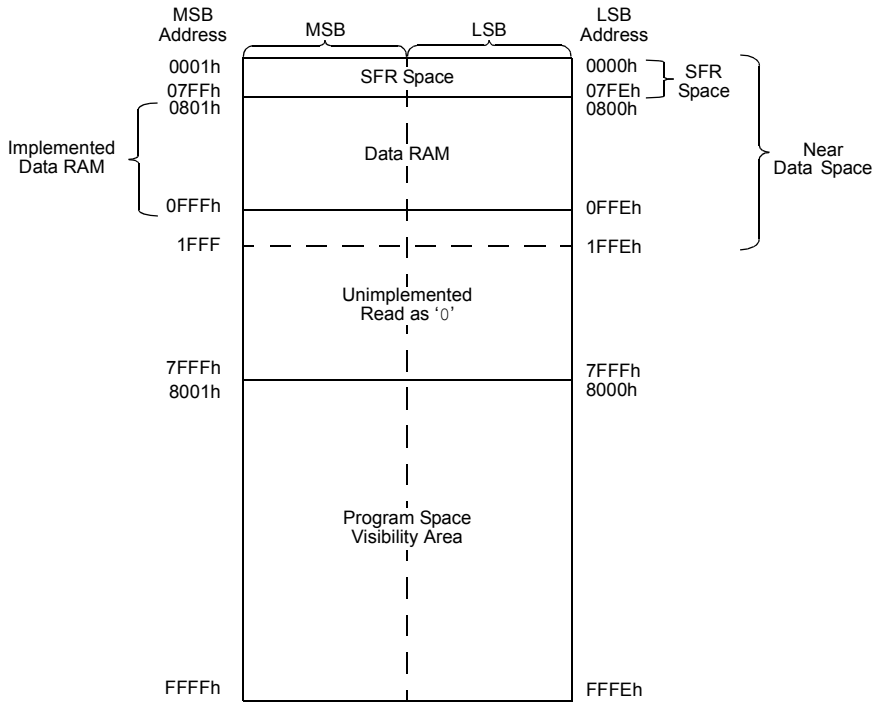
All Effective Addresses (EAs) in the data memory space are 16 bits wide and point to bytes within the data space. This gives a data space address range of 64 Kbytes or 32K words. The lower half of the data memory space (that is, when EA<15> = 0) is used for implemented memory addresses, while the upper half (EA<15> = 1) is reserved for the Program Space Visibility (PSV) area (see **Section 4.3.3 "Reading Data From Program Memory Using Program Space Visibility"**).

PIC24FV32KA304 family devices implement a total of 1024 words of data memory. If an EA points to a location outside of this area, an all zero word or byte will be returned.

4.2.1 DATA SPACE WIDTH

The data memory space is organized in byte-addressable, 16-bit wide blocks. Data is aligned in data memory and registers as 16-bit words, but all the data space EAs resolve to bytes. The Least Significant Bytes (LSBs) of each word have even addresses, while the Most Significant Bytes (MSBs) have odd addresses.

FIGURE 4-3: DATA SPACE MEMORY MAP FOR PIC24FV32KA304 FAMILY DEVICES



Note: Data memory areas are not shown to scale.

REGISTER 5-1: NVMCON: FLASH MEMORY CONTROL REGISTER

R/SO-0, HC	R/W-0	R/W-0	R/W-0	U-0	U-0	U-0	U-0
WR	WREN	WRERR	PGMONLY(4)	—	—	—	—
bit 15							bit 8

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	ERASE	NVMOP5(1)	NVMOP4(1)	NVMOP3(1)	NVMOP2(1)	NVMOP1(1)	NVMOP0(1)
bit 7							bit 0

Legend:	SO = Settable Only bit	HC = Hardware Clearable bit	
-n = Value at POR	'1' = Bit is set	R = Readable bit	W = Writable bit
'0' = Bit is cleared	x = Bit is unknown	U = Unimplemented bit, read as '0'	

bit 15 **WR:** Write Control bit
- 1 = Initiates a Flash memory program or erase operation. The operation is self-timed and the bit is cleared by hardware once the operation is complete.
- 0 = Program or erase operation is complete and inactive

bit 14 **WREN:** Write Enable bit
- 1 = Enables Flash program/erase operations
- 0 = Inhibits Flash program/erase operations

bit 13 **WRERR:** Write Sequence Error Flag bit
- 1 = An improper program or erase sequence attempt, or termination, has occurred (bit is set automatically on any set attempt of the WR bit)
- 0 = The program or erase operation completed normally

bit 12 **PGMONLY:** Program Only Enable bit(4)

bit 11-7 **Unimplemented:** Read as '0'

bit 6 **ERASE:** Erase/Program Enable bit
- 1 = Performs the erase operation specified by NVMOP<5:0> on the next WR command
- 0 = Performs the program operation specified by NVMOP<5:0> on the next WR command

bit 5-0 **NVMOP<5:0>:** Programming Operation Command Byte bits(1)

Erase Operations (when ERASE bit is '1'):
- 1010xx = Erases entire boot block (including code-protected boot block)(2)
- 1001xx = Erases entire memory (including boot block, configuration block, general block)(2)
- 011010 = Erases 4 rows of Flash memory(3)
- 011001 = Erases 2 rows of Flash memory(3)
- 011000 = Erases 1 row of Flash memory(3)
- 0101xx = Erases entire configuration block (except code protection bits)
- 0100xx = Erases entire data EEPROM(4)
- 0011xx = Erases entire general memory block programming operations
- 0001xx = Writes 1 row of Flash memory (when ERASE bit is '0')(3)

Note 1: All other combinations of NVMOP<5:0> are no operation.

2: These values are available in ICSP™ mode only. Refer to the device programming specification.

3: The address in the Table Pointer decides which rows will be erased.

4: This bit is used only while accessing data EEPROM.

REGISTER 8-2: CORCON: CPU CONTROL REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	R/C-0, HSC	R/W-0	U-0	U-0
—	—	—	—	IPL3(2)	PSV(1)	—	—
bit 7							bit 0

Legend:	C = Clearable bit	HSC = Hardware Settable/Clearable bit	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-4 **Unimplemented:** Read as '0'

bit 3 **IPL3:** CPU Interrupt Priority Level Status bit(2)
1 = CPU Interrupt Priority Level is greater than 7
0 = CPU Interrupt Priority Level is 7 or less

bit 1-0 **Unimplemented:** Read as '0'

Note 1: See Register 3-2 for the description of this bit, which is not dedicated to interrupt control functions.
2: The IPL3 bit is concatenated with the IPL<2:0> bits (SR<7:5>) to form the CPU Interrupt Priority Level.

Note: Bit 2 is described in **Section 3.0 "CPU"**.

REGISTER 8-14: IEC3: INTERRUPT ENABLE CONTROL REGISTER 3

U-0	R/W-0	U-0	U-0	U-0	U-0	U-0	U-0
—	RTCIE	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	U-0
—	—	—	—	—	MI2C2IE	SI2C2IE	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as '0'

bit 14 **RTCIE:** Real-Time Clock and Calendar Interrupt Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

bit 13-3 **Unimplemented:** Read as '0'

bit 2 **MI2C2IE:** Master I2C2 Event Interrupt Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

bit 1 **SI2C2IE:** Slave I2C2 Event Interrupt Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

bit 0 **Unimplemented:** Read as '0'

REGISTER 8-21: IPC4: INTERRUPT PRIORITY CONTROL REGISTER 4

U-0	R/W-1	R/W-0	R/W-0	U-0	R/W-1	R/W-0	R/W-0
—	CNIP2	CNIP1	CNIP0	—	CMIP2	CMIP1	CMIP0
bit 15							bit 8

U-0	R/W-1	R/W-0	R/W-0	U-0	R/W-1	R/W-0	R/W-0
—	MI2C1P2	MI2C1P1	MI2C1P0	—	SI2C1P2	SI2C1P1	SI2C1P0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as '0'

bit 14-12 **CNIP<2:0>:** Input Change Notification Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 11 **Unimplemented:** Read as '0'

bit 10-8 **CMIP<2:0>:** Comparator Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 7 **Unimplemented:** Read as '0'

bit 6-4 **MI2C1P<2:0>:** Master I2C1 Event Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 3 **Unimplemented:** Read as '0'

bit 2-0 **SI2C1P<2:0>:** Slave I2C1 Event Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

9.0 OSCILLATOR CONFIGURATION

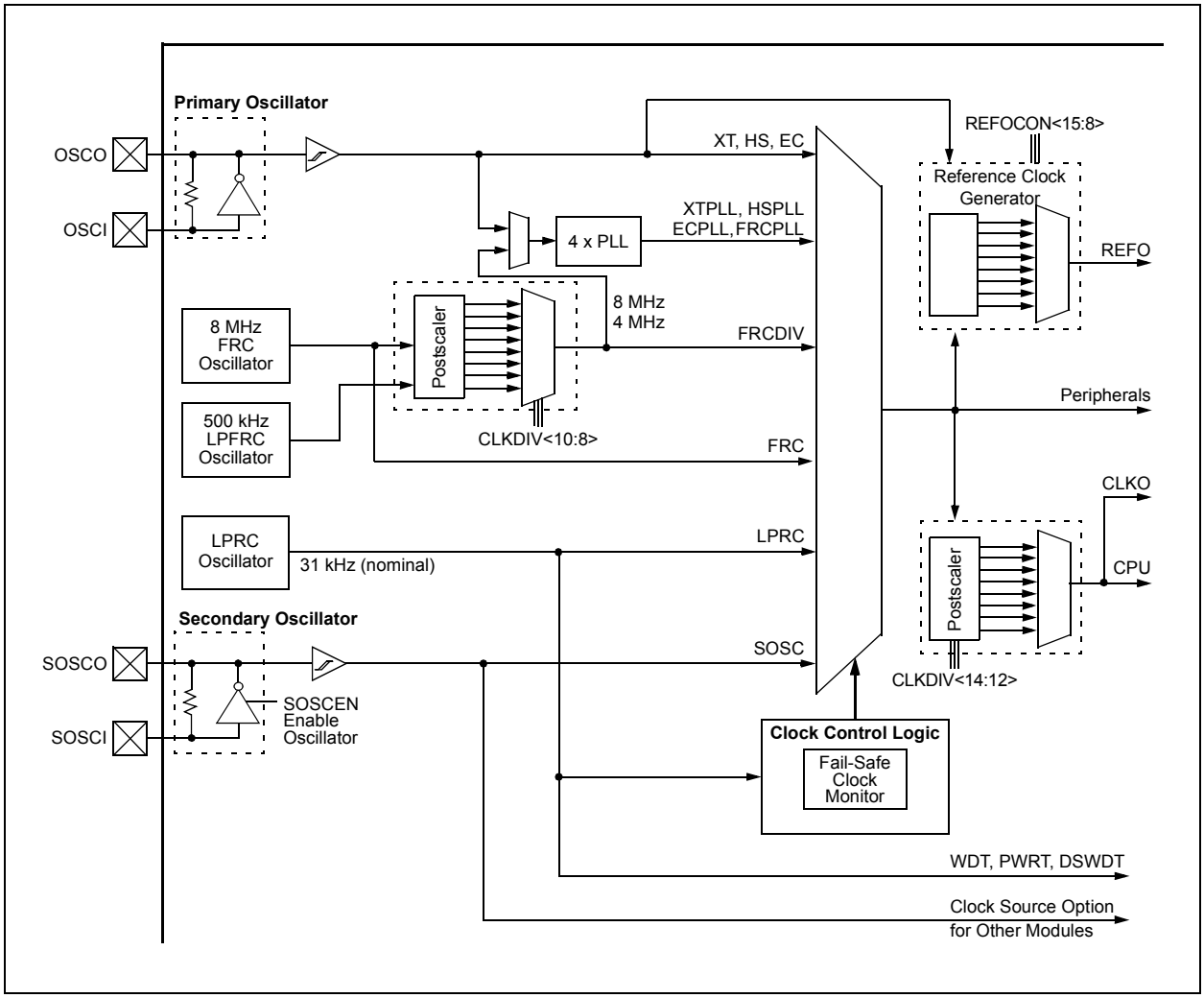
Note: This data sheet summarizes the features of this group of PIC24F devices. It is not intended to be a comprehensive reference source. For more information on Oscillator Configuration, refer to the *"PIC24F Family Reference Manual"*, **Section 38. "Oscillator with 500 kHz Low-Power FRC"** (DS39726).

The oscillator system for the PIC24FV32KA304 family of devices has the following features:

- A total of five external and internal oscillator options as clock sources, providing 11 different clock modes.
- On-chip 4x Phase Locked Loop (PLL) to boost internal operating frequency on select internal and external oscillator sources.
- Software-controllable switching between various clock sources.
- Software-controllable postscaler for selective clocking of CPU for system power savings.
- System frequency range declaration bits for EC mode. When using an external clock source, the current consumption is reduced by setting the declaration bits to the expected frequency range.
- A Fail-Safe Clock Monitor (FSCM) that detects clock failure and permits safe application recovery or shutdown.

A simplified diagram of the oscillator system is shown in Figure 9-1.

FIGURE 9-1: PIC24FV32KA304 FAMILY CLOCK DIAGRAM



10.5 Doze Mode

Generally, changing clock speed and invoking one of the power-saving modes are the preferred strategies for reducing power consumption. There may be circumstances, however, where this is not practical. For example, it may be necessary for an application to maintain uninterrupted synchronous communication, even while it is doing nothing else. Reducing system clock speed may introduce communication errors, while using a power-saving mode may stop communications completely.

Doze mode is a simple and effective alternative method to reduce power consumption while the device is still executing code. In this mode, the system clock continues to operate from the same source and at the same speed. Peripheral modules continue to be clocked at the same speed, while the CPU clock speed is reduced. Synchronization between the two clock domains is maintained, allowing the peripherals to access the SFRs while the CPU executes code at a slower rate.

Doze mode is enabled by setting the DOZEN bit (CLKDIV<11>). The ratio between peripheral and core clock speed is determined by the DOZE<2:0> bits (CLKDIV<14:12>). There are eight possible configurations, from 1:1 to 1:128, with 1:1 being the default.

It is also possible to use Doze mode to selectively reduce power consumption in event driven applications. This allows clock-sensitive functions, such as synchronous communications, to continue without interruption. Meanwhile, the CPU Idles, waiting for something to invoke an interrupt routine. Enabling the automatic return to full-speed CPU operation on interrupts is enabled by setting the ROI bit (CLKDIV<15>). By default, interrupt events have no effect on Doze mode operation.

10.6 Selective Peripheral Module Control

Idle and Doze modes allow users to substantially reduce power consumption by slowing or stopping the CPU clock. Even so, peripheral modules still remain clocked, and thus, consume power. There may be cases where the application needs what these modes do not provide: the allocation of power resources to CPU processing, with minimal power consumption from the peripherals.

PIC24F devices address this requirement by allowing peripheral modules to be selectively disabled, reducing or eliminating their power consumption. This can be done with two control bits:

- The Peripheral Enable bit, generically named, “XXXEN”, located in the module’s main control SFR.
- The Peripheral Module Disable (PMD) bit, generically named, “XXXMD”, located in one of the PMD Control registers.

Both bits have similar functions in enabling or disabling its associated module. Setting the PMDx bits for a module disables all clock sources to that module, reducing its power consumption to an absolute minimum. In this state, the control and status registers associated with the peripheral will also be disabled, so writes to those registers will have no effect, and read values will be invalid. Many peripheral modules have a corresponding PMDx bit.

In contrast, disabling a module by clearing its XXXEN bit, disables its functionality, but leaves its registers available to be read and written to. Power consumption is reduced, but not by as much as the PMDx bits are used. Most peripheral modules have an enable bit; exceptions include capture, compare and RTCC.

To achieve more selective power savings, peripheral modules can also be selectively disabled when the device enters Idle mode. This is done through the control bit of the generic name format, “XXXIDL”. By default, all modules that can operate during Idle mode will do so. Using the disable on Idle feature disables the module while in Idle mode, allowing further reduction of power consumption during Idle mode, enhancing power savings for extremely critical power applications.

REGISTER 13-1: TxCON: TIMER2 AND TIMER4 CONTROL REGISTER

R/W-0	U-0	R/W-0	U-0	U-0	U-0	U-0	U-0
TON	—	TSIDL	—	—	—	—	—
bit 15							bit 8

U-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0	U-0
—	TGATE	TCKPS1	TCKPS0	T32(1)	—	TCS	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **TON:** Timerx On bit
When TxCON<3> = 1:
1 = Starts 32-bit Timerx/y
0 = Stops 32-bit Timerx/y
When TxCON<3> = 0:
1 = Starts 16-bit Timerx
0 = Stops 16-bit Timerx

bit 14 **Unimplemented:** Read as '0'

bit 13 **TSIDL:** Timerx Stop in Idle Mode bit
1 = Discontinues module operation when device enters Idle mode
0 = Continues module operation in Idle mode

bit 12-7 **Unimplemented:** Read as '0'

bit 6 **TGATE:** Timerx Gated Time Accumulation Enable bit
When TCS = 1:
This bit is ignored.
When TCS = 0:
1 = Gated time accumulation is enabled
0 = Gated time accumulation is disabled

bit 5-4 **TCKPS<1:0>:** Timerx Input Clock Prescale Select bits
11 = 1:256
10 = 1:64
01 = 1:8
00 = 1:1

bit 3 **T32:** 32-Bit Timer Mode Select bit(1)
1 = Timer2 and Timer3 or Timer4 and Timer5 form a single 32-bit timer
0 = Timer2 and Timer3 or Timer4 and Timer5 act as two 16-bit timers

bit 2 **Unimplemented:** Read as '0'

bit 1 **TCS:** Timerx Clock Source Select bit
1 = External clock from pin, TxCK (on the rising edge)
0 = Internal clock (FOSC/2)

bit 0 **Unimplemented:** Read as '0'

Note 1: In 32-bit mode, the T3CON or T5CON control bits do not affect 32-bit timer operation.

REGISTER 13-2: TyCON: TIMER3 AND TIMER5 CONTROL REGISTER

R/W-0	U-0	R/W-0	U-0	U-0	U-0	U-0	U-0
TON(1)	—	TSIDL(1)	—	—	—	—	—
bit 15							bit 8

U-0	R/W-0	R/W-0	R/W-0	U-0	U-0	R/W-0	U-0
—	TGATE(1)	TCKPS1(1)	TCKPS0(1)	—	—	TCS(1)	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **TON:** Timery On bit(1)
1 = Starts 16-bit Timery
0 = Stops 16-bit Timery

bit 14 **Unimplemented:** Read as '0'

bit 13 **TSIDL:** Timery Stop in Idle Mode bit(1)
1 = Discontinues module operation when device enters Idle mode
0 = Continues module operation in Idle mode

bit 12-7 **Unimplemented:** Read as '0'

bit 6 **TGATE:** Timery Gated Time Accumulation Enable bit(1)
When TCS = 1:
This bit is ignored.
When TCS = 0:
1 = Gated time accumulation is enabled
0 = Gated time accumulation is disabled

bit 5-4 **TCKPS<1:0>:** Timery Input Clock Prescale Select bits(1)
11 = 1:256
10 = 1:64
01 = 1:8
00 = 1:1

bit 3-2 **Unimplemented:** Read as '0'

bit 1 **TCS:** Timery Clock Source Select bit(1)
1 = External clock is from the T3CK pin (on the rising edge)
0 = Internal clock (FOSC/2)

bit 0 **Unimplemented:** Read as '0'

Note 1: When 32-bit operation is enabled (TxCON<3> = 1), these bits have no effect on Timery operation. All timer functions are set through the TxCON register.

REGISTER 16-1: SPIxSTAT: SPIx STATUS AND CONTROL REGISTER

R/W-0	U-0	R/W-0	U-0	U-0	R-0, HSC	R-0, HSC	R-0, HSC
SPIEN	—	SPISIDL	—	—	SPIBEC2	SPIBEC1	SPIBEC0
bit 15							bit 8

R-0, HSC	R/C-0, HS	R/W-0, HSC	R/W-0	R/W-0	R/W-0	R-0, HSC	R-0, HSC
SRMPT	SPIROV	SRXMPT	SISEL2	SISEL1	SISEL0	SPITBF	SPIRBF
bit 7							bit 0

Legend:	C = Clearable bit	HS = Hardware Settable bit	HSC = Hardware Settable/Clearable bit
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **SPIEN:** SPIx Enable bit
1 = Enables module and configures SCKx, SDOx, SDIx and $\overline{SSx}$ as serial port pins
0 = Disables module

bit 14 **Unimplemented:** Read as '0'

bit 13 **SPISIDL:** SPIx Stop in Idle Mode bit
1 = Discontinues module operation when device enters Idle mode
0 = Continues module operation in Idle mode

bit 12-11 **Unimplemented:** Read as '0'

bit 10-8 **SPIBEC<2:0>:** SPIx Buffer Element Count bits (valid in Enhanced Buffer mode)
Master mode:
Number of SPI transfers pending.
Slave mode:
Number of SPI transfers unread.

bit 7 **SRMPT:** SPIx Shift Register (SPIxSR) Empty bit (valid in Enhanced Buffer mode)
1 = SPIx Shift register is empty and ready to send or receive
0 = SPIx Shift register is not empty

bit 6 **SPIROV:** SPIx Receive Overflow Flag bit
1 = A new byte/word is completely received and discarded (the user software has not read the previous data in the SPI1BUF register)
0 = No overflow has occurred

bit 5 **SRXMPT:** SPIx Receive FIFO Empty bit (valid in Enhanced Buffer mode)
1 = Receive FIFO is empty
0 = Receive FIFO is not empty

bit 4-2 **SISEL<2:0>:** SPIx Buffer Interrupt Mode bits (valid in Enhanced Buffer mode)
111 = Interrupt when SPIx transmit buffer is full (SPITBF bit is set)
110 = Interrupt when last bit is shifted into SPIxSR; as a result, the TX FIFO is empty
101 = Interrupt when the last bit is shifted out of SPIxSR; now the transmit is complete
100 = Interrupt when one data byte is shifted into the SPIxSR; as a result, the TX FIFO has one open spot
011 = Interrupt when SPIx receive buffer is full (SPIRBF bit is set)
010 = Interrupt when SPIx receive buffer is 3/4 or more full
001 = Interrupt when data is available in receive buffer (SRMPT bit is set)
000 = Interrupt when the last data in the receive buffer is read; as a result, the buffer is empty (SRXMPT bit is set)

REGISTER 18-3: UxTXREG: UARTx TRANSMIT REGISTER

U-x	U-x	U-x	U-x	U-x	U-x	U-x	W-x
—	—	—	—	—	—	—	UTX8
bit 15							bit 8

W-x	W-x	W-x	W-x	W-x	W-x	W-x	W-x
UTX7	UTX6	UTX5	UTX4	UTX3	UTX2	UTX1	UTX0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-9 **Unimplemented:** Read as '0'
bit 8 **UTX8:** UARTx Data of the Transmitted Character bit (in 9-bit mode)
bit 7-0 **UTX<7:0>:** UARTx Data of the Transmitted Character bits

REGISTER 18-4: UxRXREG: UARTx RECEIVE REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	R-0, HSC
—	—	—	—	—	—	—	URX8
bit 15							bit 8

R-0, HSC	R-0, HSC	R-0, HSC	R-0, HSC	R-0, HSC	R-0, HSC	R-0, HSC	R-0, HSC
URX7	URX6	URX5	URX4	URX3	URX2	URX1	URX0
bit 7							bit 0

Legend:	HSC = Hardware Settable/Clearable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-9 **Unimplemented:** Read as '0'
bit 8 **URX8:** UARTx Data of the Received Character bit (in 9-bit mode)
bit 7-0 **URX<7:0>:** UARTx Data of the Received Character bits

REGISTER 19-3: ALCFGRPT: ALARM CONFIGURATION REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ALRMEN	CHIME	AMASK3	AMASK2	AMASK1	AMASK0	ALRMPTR1	ALRMPTR0
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ARPT7	ARPT6	ARPT5	ARPT4	ARPT3	ARPT2	ARPT1	ARPT0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **ALRMEN:** Alarm Enable bit

1 = Alarm is enabled (cleared automatically after an alarm event whenever ARPT<7:0> = 00h and CHIME = 0)

0 = Alarm is disabled

bit 14 **CHIME:** Chime Enable bit

1 = Chime is enabled; ARPT<7:0> bits are allowed to roll over from 00h to FFh

0 = Chime is disabled; ARPT<7:0> bits stop once they reach 00h

bit 13-10 **AMASK<3:0>:** Alarm Mask Configuration bits

0000 = Every half second
0001 = Every second
0010 = Every 10 seconds
0011 = Every minute
0100 = Every 10 minutes
0101 = Every hour
0110 = Once a day
0111 = Once a week
1000 = Once a month
1001 = Once a year (except when configured for February 29th, once every 4 years)
101x = Reserved – do not use
11xx = Reserved – do not use

bit 9-8 **ALRMPTR<1:0>:** Alarm Value Register Window Pointer bits

Points to the corresponding Alarm Value registers when reading the ALRMVALH and ALRMVALL registers. The ALRMPTR<1:0> value decrements on every read or write of ALRMVALH until it reaches '00'.

ALRMVAL<15:8>:
00 = ALRMMIN
01 = ALRMWD
10 = ALRMMNTH
11 = Unimplemented

ALRMVAL<7:0>:
00 = ALRMSEC
01 = ALRMHR
10 = ALRMDAY
11 = Unimplemented

bit 7-0 **ARPT<7:0>:** Alarm Repeat Counter Value bits

11111111 = Alarm will repeat 255 more times
.
.
.
00000000 = Alarm will not repeat

The counter decrements on any alarm event; it is prevented from rolling over from 00h to FFh unless CHIME = 1.

REGISTER 20-1: CRCCON1: CRC CONTROL REGISTER 1

R/W-0	U-0	R/W-0	R-0	R-0	R-0	R-0	R-0
CRCEN	—	CSIDL	VWORD4	VWORD3	VWORD2	VWORD1	VWORD0
bit 15							bit 8

R-0, HSC	R-1, HSC	R/W-0	R/W-0, HC	R/W-0	U-0	U-0	U-0
CRCFUL	CRCMPT	CRCISEL	CRCGO	LENDIAN	—	—	—
bit 7							bit 0

Legend:	HC = Hardware Clearable bit	HSC = Hardware Settable/Clearable bit	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **CRCEN**: CRC Enable bit
1 = Module is enabled
0 = Module is enabled
All state machines, pointers and CRCWDAT/CRCDAT registers are reset; other SFRs are NOT reset.

bit 14 **Unimplemented:** Read as '0'

bit 13 **CSIDL:** CRC Stop in Idle Mode bit
1 = Discontinues module operation when device enters Idle mode
0 = Continues module operation in Idle mode

bit 12-8 **VWORD<4:0>:** Pointer Value bits
Indicates the number of valid words in the FIFO, which has a maximum value of 8 when PLEN<4:0> > 7 or 16 when PLEN<4:0> ≤ 7.

bit 7 **CRCFUL**: CRC FIFO Full bit
1 = FIFO is full
0 = FIFO is not full

bit 6 **CRCMPT:** CRC FIFO Empty Bit
1 = FIFO is empty
0 = FIFO is not empty

bit 5 **CRCISEL:** CRC interrupt Selection bit
1 = Interrupt on FIFO is empty; CRC calculation is not complete
0 = Interrupt on shift is complete and CRCWDAT result is ready

bit 4 **CRCGO:** Start CRC bit
1 = Starts CRC serial shifter
0 = CRC serial shifter is turned off

bit 3 **LENDIAN:** Data Shift Direction Select bit
1 = Data word is shifted into the CRC, starting with the LSb (little endian)
0 = Data word is shifted into the CRC, starting with the MSb (big endian)

bit 2-0 **Unimplemented:** Read as '0'

22.0 12-BIT A/D CONVERTER WITH THRESHOLD DETECT

Note: This data sheet summarizes the features of this group of PIC24F devices. It is not intended to be a comprehensive reference source. For more information on the 12-Bit A/D Converter with Threshold Detect, refer to the *"PIC24F Family Reference Manual"*, **Section 51. "12-Bit A/D Converter with Threshold Detect"** (DS39739).

The PIC24F 12-bit A/D Converter has the following key features:

- Successive Approximation Register (SAR) Conversion
- Conversion Speeds of up to 100 ksps
- Up to 32 Analog Input Channels (Internal and External)
- Multiple Internal Reference Input Channels
- External Voltage Reference Input Pins
- Unipolar Differential Sample-and-Hold (S/H) Amplifier
- Automated Threshold Scan and Compare Operation to Pre-Evaluate Conversion Results
- Selectable Conversion Trigger Source
- Fixed-Length (one word per channel), Configurable Conversion Result Buffer
- Four Options for Results Alignment
- Configurable Interrupt Generation
- Operation During CPU Sleep and Idle modes

The 12-bit A/D Converter module is an enhanced version of the 10-bit module offered in some PIC24 devices. Both modules are Successive Approximation Register (SAR) converters at their cores, surrounded by a range of hardware features for flexible configuration. This version of the module extends functionality by providing 12-bit resolution, a wider range of automatic sampling options and tighter integration with other analog modules, such as the CTMU and a configurable results buffer. This module also includes a unique Threshold Detect feature that allows the module itself to make simple decisions based on the conversion results.

A simplified block diagram for the module is illustrated in Figure 22-1.

27.7 MPLAB SIM Software Simulator

The MPLAB SIM Software Simulator allows code development in a PC-hosted environment by simulating the PIC MCUs and dsPIC® DSCs on an instruction level. On any given instruction, the data areas can be examined or modified and stimuli can be applied from a comprehensive stimulus controller. Registers can be logged to files for further run-time analysis. The trace buffer and logic analyzer display extend the power of the simulator to record and track program execution, actions on I/O, most peripherals and internal registers.

The MPLAB SIM Software Simulator fully supports symbolic debugging using the MPLAB C Compilers, and the MPASM and MPLAB Assemblers. The software simulator offers the flexibility to develop and debug code outside of the hardware laboratory environment, making it an excellent, economical software development tool.

27.8 MPLAB REAL ICE In-Circuit Emulator System

MPLAB REAL ICE In-Circuit Emulator System is Microchip's next generation high-speed emulator for Microchip Flash DSC and MCU devices. It debugs and programs PIC® Flash MCUs and dsPIC® Flash DSCs with the easy-to-use, powerful graphical user interface of the MPLAB Integrated Development Environment (IDE), included with each kit.

The emulator is connected to the design engineer's PC using a high-speed USB 2.0 interface and is connected to the target with either a connector compatible with in-circuit debugger systems (RJ11) or with the new high-speed, noise tolerant, Low-Voltage Differential Signal (LVDS) interconnection (CAT5).

The emulator is field upgradable through future firmware downloads in MPLAB IDE. In upcoming releases of MPLAB IDE, new devices will be supported, and new features will be added. MPLAB REAL ICE offers significant advantages over competitive emulators including low-cost, full-speed emulation, run-time variable watches, trace analysis, complex breakpoints, a ruggedized probe interface and long (up to three meters) interconnection cables.

27.9 MPLAB ICD 3 In-Circuit Debugger System

MPLAB ICD 3 In-Circuit Debugger System is Microchip's most cost effective high-speed hardware debugger/programmer for Microchip Flash Digital Signal Controller (DSC) and microcontroller (MCU) devices. It debugs and programs PIC® Flash microcontrollers and dsPIC® DSCs with the powerful, yet easy-to-use graphical user interface of MPLAB Integrated Development Environment (IDE).

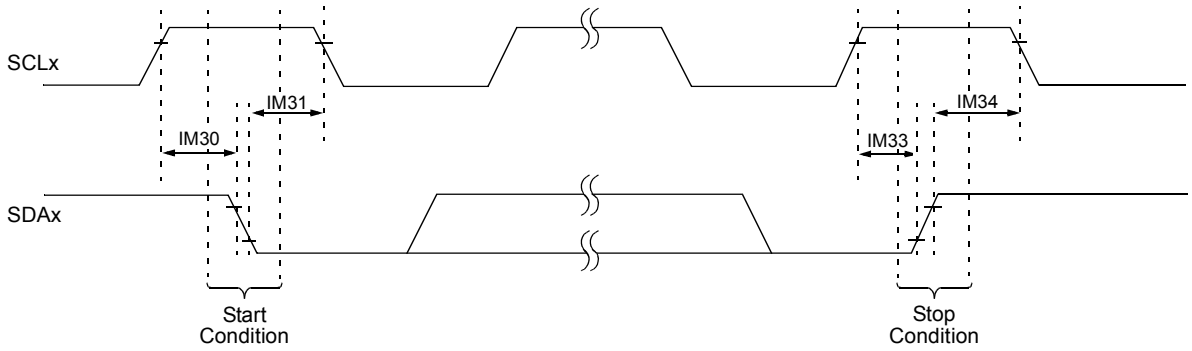
The MPLAB ICD 3 In-Circuit Debugger probe is connected to the design engineer's PC using a high-speed USB 2.0 interface and is connected to the target with a connector compatible with the MPLAB ICD 2 or MPLAB REAL ICE systems (RJ-11). MPLAB ICD 3 supports all MPLAB ICD 2 headers.

27.10 PICkit 3 In-Circuit Debugger/ Programmer and PICkit 3 Debug Express

The MPLAB PICkit 3 allows debugging and programming of PIC® and dsPIC® Flash microcontrollers at a most affordable price point using the powerful graphical user interface of the MPLAB Integrated Development Environment (IDE). The MPLAB PICkit 3 is connected to the design engineer's PC using a full speed USB interface and can be connected to the target via an Microchip debug (RJ-11) connector (compatible with MPLAB ICD 3 and MPLAB REAL ICE). The connector uses two device I/O pins and the reset line to implement in-circuit debugging and In-Circuit Serial Programming™.

The PICkit 3 Debug Express include the PICkit 3, demo board and microcontroller, hookup cables and CDROM with user's guide, lessons, tutorial, compiler and MPLAB IDE software.

FIGURE 29-12: I²C™ BUS START/STOP BITS TIMING CHARACTERISTICS (MASTER MODE)



Note: Refer to Figure 29-3 for load conditions.

TABLE 29-31: I²C™ BUS START/STOP BIT TIMING REQUIREMENTS (MASTER MODE)

AC CHARACTERISTICS				Standard Operating Conditions: 2.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial) -40°C ≤ TA ≤ +125°C for Extended			
Param No.	**Symbol**	**Characteristic**		**Min(1)**	**Max**	**Units**	**Conditions**
IM30	TSU:STA	Start Condition Setup Time	100 kHz mode	TCY/2 (BRG + 1)	—	µs	Only relevant for Repeated Start condition
			400 kHz mode	TCY/2 (BRG + 1)	—	µs	
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	µs	
IM31	THD:STA	Start Condition Hold Time	100 kHz mode	TCY/2 (BRG + 1)	—	µs	After this period, the first clock pulse is generated
			400 kHz mode	TCY/2 (BRG + 1)	—	µs	
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	µs	
IM33	TSU:STO	Stop Condition Setup Time	100 kHz mode	TCY/2 (BRG + 1)	—	µs	
			400 kHz mode	TCY/2 (BRG + 1)	—	µs	
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	µs	
IM34	THD:STO	Stop Condition Hold Time	100 kHz mode	TCY/2 (BRG + 1)	—	ns	
			400 kHz mode	TCY/2 (BRG + 1)	—	ns	
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	ns	

Note 1: BRG is the value of the I²C™ Baud Rate Generator. Refer to **Section 17.3 "Setting Baud Rate When Operating as a Bus Master"** for details.

2: Maximum pin capacitance = 10 pF for all I²C pins (for 1 MHz mode only).

FIGURE 29-20: SPIx MODULE SLAVE MODE TIMING CHARACTERISTICS (CKE = 0)

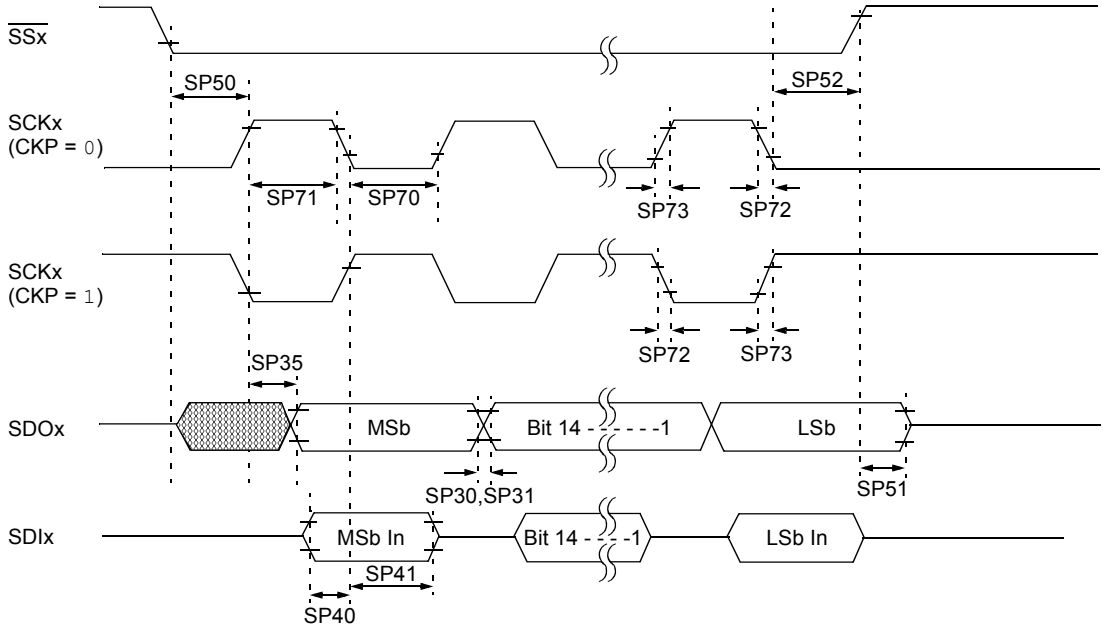


TABLE 29-38: SPIx MODULE SLAVE MODE TIMING REQUIREMENTS (CKE = 0)

AC CHARACTERISTICS			Standard Operating Conditions: 2.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ(1)**	**Max**	**Units**	**Conditions**
SP70	TscL	SCKx Input Low Time	30	—	—	ns	
SP71	TscH	SCKx Input High Time	30	—	—	ns	
SP72	TscF	SCKx Input Fall Time(2)	—	10	25	ns	
SP73	TscR	SCKx Input Rise Time(2)	—	10	25	ns	
SP30	TdoF	SDOx Data Output Fall Time(2)	—	10	25	ns	
SP31	TdoR	SDOx Data Output Rise Time(2)	—	10	25	ns	
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	—	30	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	20	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	20	—	—	ns	
SP50	TssL2scH, TssL2scL	$\overline{SSx}$ to SCKx ↑ or SCKx Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{SSx}$ ↑ to SDOx Output High-Impedance(3)	10	—	50	ns	
SP52	TscH2ssH TscL2ssH	$\overline{SSx}$ after SCKx Edge	1.5 TCY + 40	—	—	ns	

Note 1: Data in "Typ" column is at 3.3V, +25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

2: The minimum clock period for SCKx is 100 ns; therefore, the clock generated in Master mode must not violate this specification.

3: This assumes a 50 pF load on all SPIx pins.

FIGURE 30-53: VIL/VIH vs. VDD (OSCO, TEMPERATURES AS NOTED)

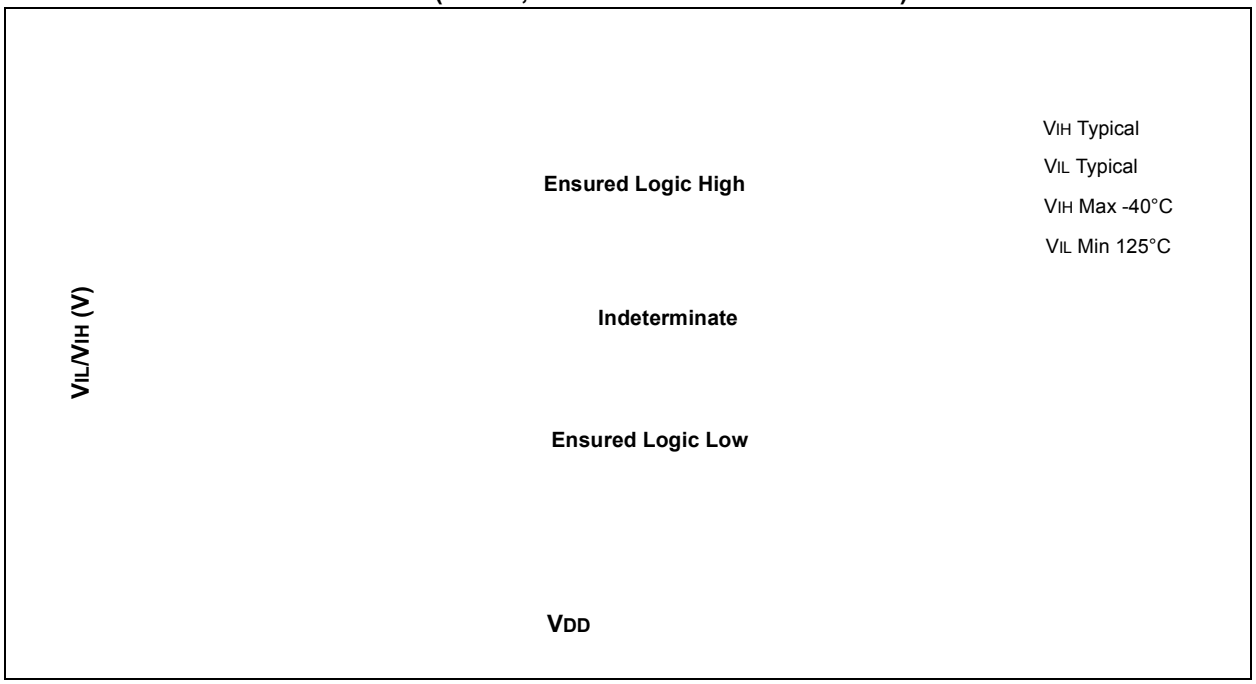


FIGURE 30-54: VIL/VIH vs. VDD ($\overline{\text{MCLR}}$, TEMPERATURES AS NOTED)